

CONDUCTIVE PASTE

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Inventor: TANI KOJI; others: 01
Applicant: MURATA MFG CO LTD
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Abstract of JP5234414

PURPOSE: To prevent generation of a warp and a crack on a chip element so as to improve an yield of a product by dispersing a specific amount of copper powder in an organic vehicle.
CONSTITUTION: Copper powder 40 to 70wt.% is dispersed in an organic vehicle so as to obtain a conductive paste. Since this paste is made into a glass fritless containing no glass frit having a large coefficient of heat contraction, the coefficient of heat contraction is small resulting in thinner coat. Further, generation of firing blister in an outer electrode can be suppressed.

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